PFR®-800 AUS®SR1 (Trial #64329)

FC用現像型ソルダーレジストドライフィルム

Dry Film Solder Mask for Flip Chip Substrate Application

主な特徴 Feature

- **投影露光 /DI露光対応**
  Product line up suitable to various exposure units (Projection, LDI multi)
- **高Tg/低CTE材：優れたTCT/PCT耐性**
  Tough resin structure with High Tg/Low CTE for TCT and PCT resistance
- **高精細での優れた電気特性**
  Electrical reliability: No migration failure with L/S=15/10μm after 200hrs, 12V, 130℃/85%Rh
- **徹底した粗粒管理**
  Strict control on particle size: Max.particle size <10μm Majority part is sub-micron order

仕様 Specification

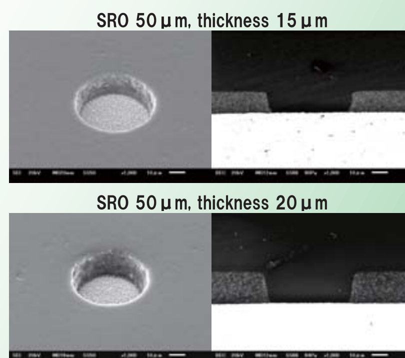
膜厚 Resin thickness	20μm (standard) – Adjustable
色調 Color	Green
保管条件 Storage condition	Below -15℃
推奨硬化条件 Recommended curing condition	160℃, 60min.

特性 Properties

ガラス移転点 Tg ＊TMA method		130 – 140 ℃
線膨張係数 CTE	α1	40 – 45 ppm
弾性率 Young's modulus		3.5 – 4.0 GPa
破壊強度 Tensile strength		70 – 75 MPa
破壊伸び率 Elongation		3.5 – 4.0 %
感度 Photosensitivity		350 mJ/cm²
解像性 SRO resolution		50 μm in diameter
PCT耐性 (121℃, 2 .1atm, 100%Rh, 200hrs)		No peering
HAST耐性 (130℃, 85%Rh, 12V, 168hrs, L/S=15/10μm)		No migration
TCT耐性 (-65 ⇔ 150℃, 1000cycles)		Pass

After 217hrs HAST
130℃85% 12V

SRO 50μm, thickness 15μm



SRO 50μm, thickness 20μm

TAIYO INK MFG. CO., LTD.